

2026 MPW schedule

Last updated: December 9, 2025

MPW name	Fab	Processes	Tape-In	Ship Date
PH18DA - B6006	NPB - Fab 3	SiPho 0.18um	3-25-25	1-16-26
SB*18 - B6007	TSSA - Fab 9	SiGe BiCMOS 0.18um	4-08-25	**
Q2 2025	NM - Fab 11	TNM65MSPM	5-15-25	**
PH18M* - B6010	NPB - Fab 3	SiPho 0.18um	5-20-25	1-12-26
SB*18 - B6011	NPB - Fab 3	SiGe BiCMOS 0.18um	6-03-25	12-22-25
SB*18 - B6015	NPB - Fab 3	SiGe BiCMOS 0.18um	7-29-25	2-16-26
PH18DA - B6016	NPB - Fab 3	SiPho 0.18um	8-12-25	6-12-26
Q3 2025	NM - Fab 11	TNM65MSPM	8-15-25	**
CA18 - B6017	NPB - Fab 3	RFCMOS 0.18um	8-26-25	2-06-26
2nd MPW RFSOI-RSS5T	TSIT - Fab 10	90RSC/65RSA2/65RSB2/65RSC	9-8-25	**
36th MPW - Uozu, Japan	TPSCo - Fab 7	CMOS, PM, RFCMOS & SiGe, 65nm : TPS65SLA/SLC, TPS65PMA/PMB/PMK/MSA/MSB/MSK, TPS65RF, TPS65SG	9-29-25	**
SB*18 - B6020	NPB - Fab 3	SiGe BiCMOS 0.18um	10-07-25	4-16-26
SBC18HE5PCA - B6021	NPB - Fab 3	SiGe BiCMOS 0.18um with PCM RF Switch	10-21-25	**
PH18M* - B6022	NPB - Fab 3	SiPho 0.18um	10-28-25	6-22-26
SH225T18NOV	MH - Fab 2	CIS 0.18u Image Sensor CMOS+ 0.16u, 0.18u RF, RFID, PM	11-17-25 11-23-25	**
MPW - Uozu, Japan	TPSCo - Fab 7	TPS65MSPM	12-5-25	**
SB*18 - B6400	NPB - Fab 3	SiGe BiCMOS 0.18um	1-20-26	7-30-26
CA18 - B6401	NPB - Fab 3	RFCMOS 0.18um	2-03-26	7-17-26
Q1 2026	NM - Fab 11	TNM65MSPM	2-13-26	**
PH18M* - B6402	NPB - Fab 3	SiPho 0.18um	2-17-26	10-12-26
36th MPW - Tonami, Japan	TPSCo - Fab 5	CMOS 0.18u & 0.16u, PM, PM_SOI	2-24-26	**
SB*18 - B6403	NPB - Fab 3	SiGe BiCMOS 0.18um	3-03-26	9-10-26
1st MPW RFSOI-RSM6T	TSIT - Fab 10	90RSC/65RSA2/65RSB2/65RSC	3-10-26	**
PH18DA - B6404	NPB - Fab 3	SiPho 0.18um	3-17-26	1-15-27
38th MPW - Uozu, Japan	TPSCo - Fab 7	CMOS, PM, RFCMOS & SiGe, 65nm : TPS65SLA/SLC, TPS65PMA/PMB/PMK/MSA/MSB/MSK, TPS65RF, TPS65SG	3-23-26	**
SBC18HE5PCA - B6405	NPB - Fab 3	SiGe BiCMOS 0.18um with PCM RF Switch	3-31-26	**
SH126T18APR	MH - Fab 2	CIS 0.18u Image Sensor CMOS+ 0.16u, 0.18u RF, RFID, PM	4-12-26 4-20-26	**
39th MPW - Uozu, Japan	TPSCo - Fab 7	300mm Silicon Photonics: TPS45PHD	4-13-26	**

MPW name	Fab	Processes	Tape-In	Ship Date
SB*18 - B6406	TSSA - Fab 9	SiGe BiCMOS 0.18um	4-14-26	**
CA18 - B6407	NPB - Fab 3	RFCMOS 0.18um	4-28-26	11-05-26
PH18M* - B6408	NPB - Fab 3	SiPho 0.18um	5-12-26	1-04-27
Q2 2026	NM - Fab 11	TNM65MSPM	5-14-26	**
37th MPW - Tonami, Japan	TPSCo - Fab 5	CMOS 0.18u & 0.16u, PM, PM_SOI	5-25-26	**
SB*18 - B6409	NPB - Fab 3	SiGe BiCMOS 0.18um	5-26-26	12-14-26
SB*/CA13* - B6410	NPB - Fab 3	SiGe BiCMOS/RF CMOS 0.13um	6-09-26	2-9-27
PH18DA - B6411	NPB - Fab 3	SiPho 0.18um	6-23-26	4-23-27
SB*18 - B6412	NPB - Fab 3	SiGe BiCMOS 0.18um	7-14-26	2-01-27
CA18 - B6413	NPB - Fab 3	RFCMOS 0.18um	7-28-26	1-08-27
PH18M* - B6414	NPB - Fab 3	SiPho 0.18um	8-11-26	04-05-27
Q3 2026	NM - Fab 11	TNM65MSPM	8-14-26	**
38th MPW - Tonami, Japan	TPSCo - Fab 5	CMOS 0.18u & 0.16u, PM, PM_SOI	8-24-26	**
SB*18 - B6415	NPB - Fab 3	SiGe BiCMOS 0.18um	8-25-26	3-04-27
2nd MPW RFSOI-RSS6T	TSIT - Fab 10	90RSC/65RSA2/65RSB2/65RSC	9-10-26	**
SBC18HE5PCA - B6416	NPB - Fab 3	SiGe BiCMOS 0.18um with PCM RF Switch	9-15-26	**
40th MPW - Uozu, Japan	TPSCo - Fab 7	CMOS, PM, RFCMOS & SiGe, 65nm : TPS65SLA/SLC, TPS65PMA/PMB/PMK/MSA/MSB/MSK, TPS65RF, TPS65SG	9-28-26	**
SB*18 - B6417	NPB - Fab 3	SiGe BiCMOS 0.18um	10-6-26	4-15-27
41th MPW - Uozu, Japan	TPSCo - Fab 7	300mm Silicon Photonics: TPS45PHD	10-26-26	**
PH18M* - B6418	NPB - Fab 3	SiPho 0.18um	10-27-26	6-21-27
SH226T18NOV	MH - Fab 2	CIS 0.18u Image Sensor CMOS+ 0.16u, 0.18u RF, RFID, PM	11-10-26 11-17-26	**
Q4 2026	NM - Fab 11	TNM65MSPM	11-13-26	**
39th MPW - Tonami, Japan	TPSCo - Fab 5	CMOS 0.18u & 0.16u, PM, PM_SOI	11-24-26	**

Notes: "Shuttles" (SH*) are run at Fab 2

* 0.13u MH – fab 2 Shuttle / MPW slots will be considered per needs

** Contact your Account Manager for details.

Please contact your customer account manager for additional information.

Fab2 - Tower Semiconductor 200mm wafer fabrication facility at Migdal Ha'emek, Israel

Fab3 - Tower Semiconductor 200mm wafer fabrication facility at Newport Beach, CA

Fab5 - Tower Semiconductor 200mm wafer fabrication facility at Tonami, Japan

Fab7 - Tower Semiconductor 300mm wafer fabrication facility at Uozu, Japan

Fab9 - Tower Semiconductor 200mm wafer fabrication facility at San Antonio, TX

Fab10 - Tower Semiconductor 300mm wafer fabrication facility at Agrate, Italy

Fab11 - Tower Semiconductor 300mm wafer fabrication facility at Rio Rancho, NM